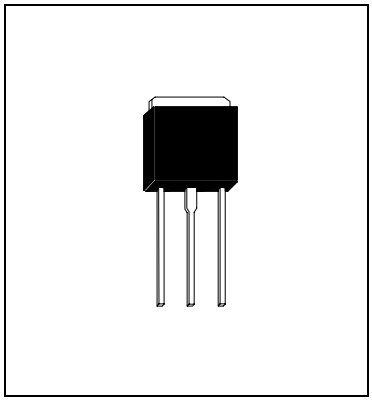
HI1109

PNP EPITAXIAL PLANAR TRANSISTOR



Description

- Low frequency high voltage amplifier
- Complementary pair with HI1609

Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
  Storage Temperature ..... -55~+150 °C
  Junction Temperature ..... +150 °C
- Maximum Power Dissipation
  Total Power Dissipation (Ta=25°C) ..... 1.25 W
- Maximum Voltages and Currents
  BVCBO Collector to Base Voltage ..... -160 V
  BVCEO Collector to Emitter Voltage ..... -160 V
  BVEBO Emitter to Base Voltage ..... -5 V
  IC Collector Current ..... -100 mA

Characteristics (Ta=25°C)

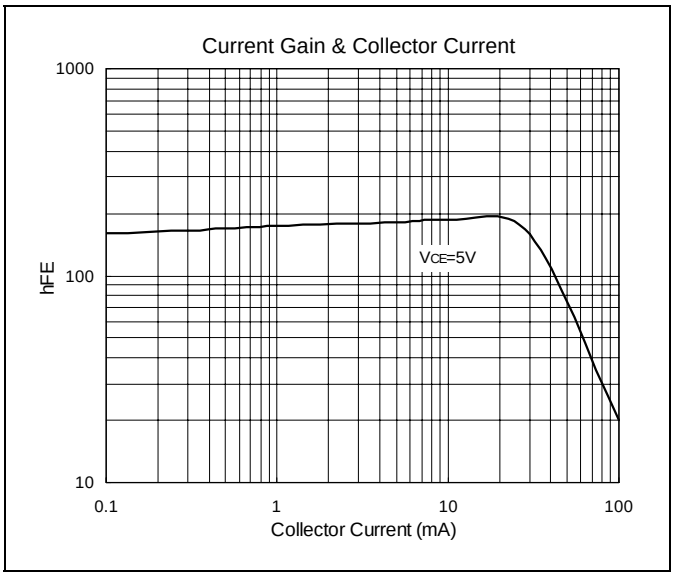
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-160	-	-	V	IC=-10uA, IE=0
BVCEO	-160	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-10	uA	VCB=-140V, IE=0
*VCE(sat)	-	-	-2	V	IC=-30mA, IB=-3mA
VBE	-	-	-1.5	V	VCE=-5V, IC=-10mA
*hFE1	60	-	320		VCE=-5V, IC=-10mA
*hFE2	30	-	-		VCE=-5V, IC=-1mA
fT	-	140	-	MHz	VCE=-5V, IC=-10mA
Cob	-	5.5	-	pF	VCB=-10V, f=-1MHz

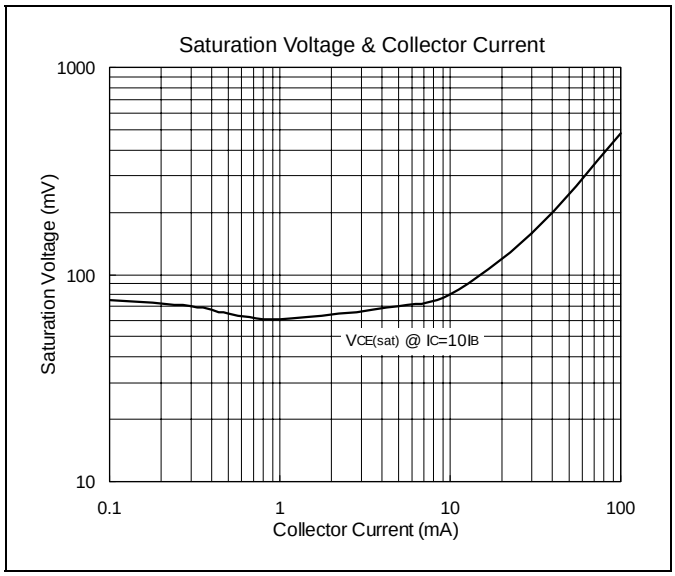
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

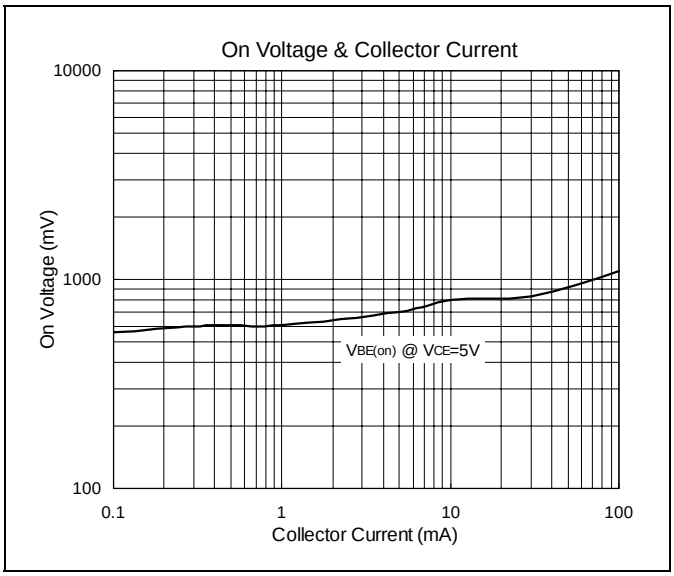
Classification Of hFE1

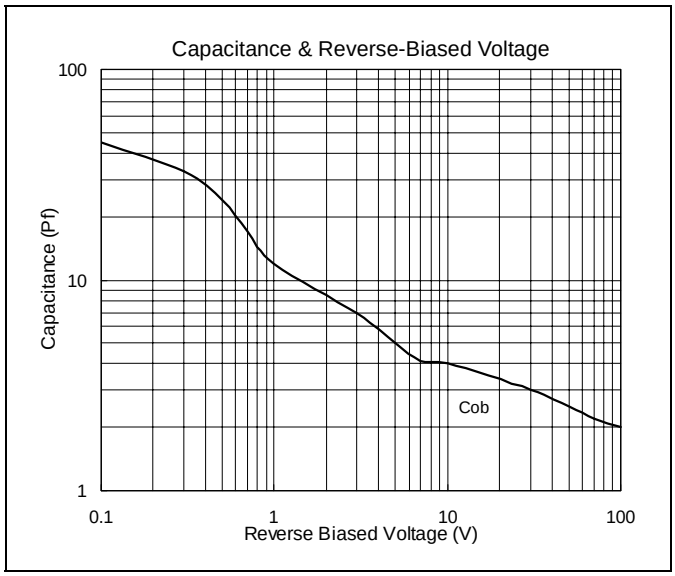
Rank	B	C	D
Range	60-120	100-200	160-320

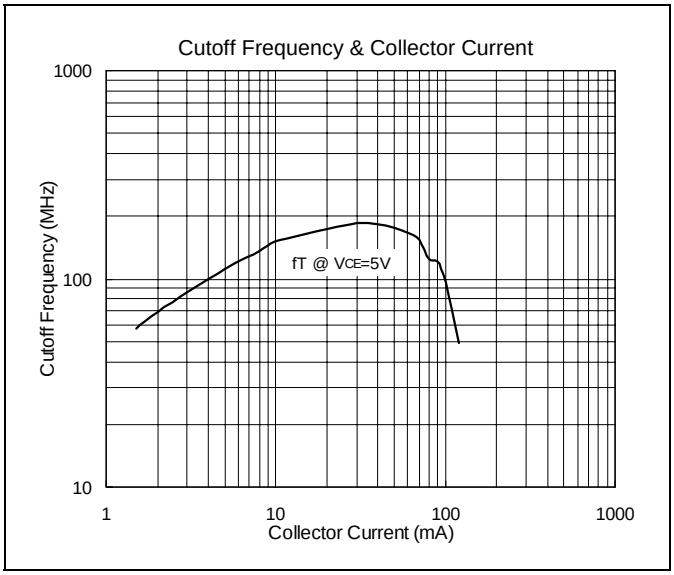
Characteristics Curve



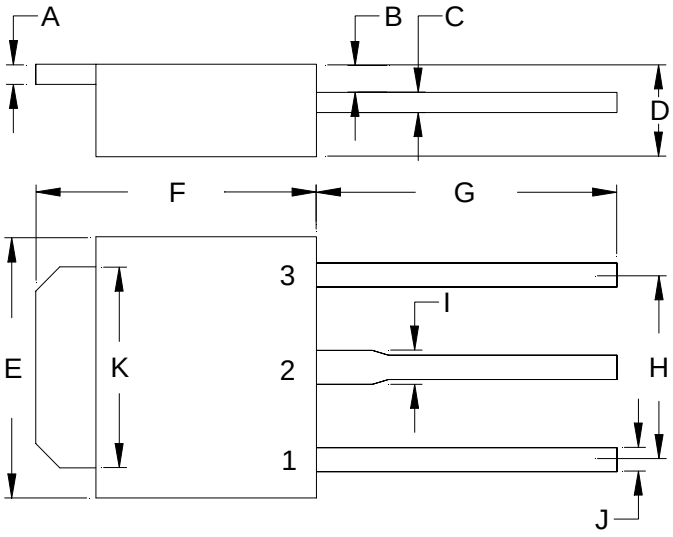




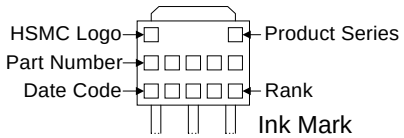




TO-251 Dimension



Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

3-Lead TO-251 Plastic Package
HSMC Package Code : I

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.2559	-	6.50	-
B	0.0354	0.0591	0.90	1.50	H	-	*0.1811	-	*4.60
C	0.0177	0.0236	0.45	0.60	I	-	0.0354	-	0.90
D	0.0866	0.0945	2.20	2.40	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2677	0.2835	6.80	7.20					

Notes : 1.Dimension and tolerance based on our Spec. dated May. 24,1995.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

Head Office And Factory :

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